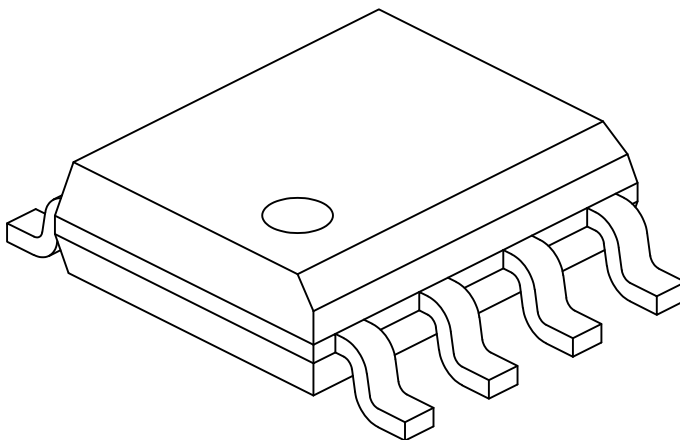


8-Lead Plastic Small Outline (S7X) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

Atmel Legacy Global Package Code SWB

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packageing>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		8		
Pitch	e		1.27 BSC		
Overall Height	A	-	-	-	1.75
Molded Package Thickness	A2		1.25	-	-
Standoff §	A1		0.10	-	0.25
Overall Width	E		6.00 BSC		
Molded Package Width	E1		3.90 BSC		
Overall Length	D		4.90 BSC		
Chamfer (Optional)	h		0.25	-	0.50
Foot Length	L		0.40	-	1.27
Footprint	L1		1.04 REF		
Lead Thickness	c		0.17	-	0.25
Lead Width	b		0.31	-	0.51
Lead Bend Radius	R		0.07	-	-
Lead Bend Radius	R1		0.07	-	-
Foot Angle	θ		0°	-	8°
Mold Draft Angle	θ1		5°	-	15°
Lead Angle	θ2		0°	-	8°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

- Datums A & B to be determined at Datum H.